

DLAP-211 Series

Ultra-Compact, Fanless, Edge AI Platform for Diverse AI Applications

Features

- Embedded with NVIDIA® Jetson Orin NX/Nano™, Xavier NX™, TX2 NX™, or Nano™ module, delivering up to 100 TOPS
- Extremely compact at 148mm x 120mm x 52mm with a fanless design
- Extended operating temperature range from -20°C to 70°C
- Versatile I/O ports with optional FM board extension
- Ideal for diverse AI applications like Smart City, Retail, Manufacturing, and more
- Development kit (without chassis SKU) is available for purchase



Ordering Information

PN	Model Name	NVIDIA Module	NVIDIA Module Memory	NVIDIA Module eMMC	NVMe	Expand IO
93-45103-0420	DLAP-211-Orin NX 16GB	Orin NX	16GB	N/A	128GB (pre-installed system)	N/A
93-45103-0320	DLAP-211-Orin NX 8GB	Orin NX	8GB	N/A	128GB (pre-installed system)	N/A
93-45103-1310	DLAP-211-Orin Nano 8GB	Orin Nano	8GB	N/A	128GB (pre-installed system)	N/A
93-45103-1210	DLAP-211-Orin Nano 4GB	Orin Nano	4GB	N/A	128GB (pre-installed system)	N/A
93-45103-0230	DLAP-211-JNX 16GB	Xavier NX	16GB	16GB (pre-installed system)	N/A	N/A
93-45103-0050	DLAP-211-JNX	Xavier NX	8GB	16GB (pre-installed system)	N/A	N/A
93-45103-6010	DLAP-211-JT2	TX2NX	4GB	16GB (pre-installed system)	N/A	N/A
93-45103-1020	DLAP-211-Nano	Nano	4GB	16GB (pre-installed system)	N/A	N/A
93-45103-4220	DLAP-211-Orin NXS 16GB	Orin NX	16GB	N/A	128GB (pre-installed system)	YES
93-45103-4410	DLAP-211-Orin NXS 8GB	Orin NX	8GB	N/A	128GB (pre-installed system)	YES
93-45103-5210	DLAP-211-Orin NanoS 8GB	Orin Nano	8GB	N/A	128GB (pre-installed system)	YES
93-45103-4020	DLAP-211-JNXS	Xavier NX	8GB	16GB (pre-installed system)	N/A	YES
93-45103-5020	DLAP-211-NanoS	Nano	4GB	16GB (pre-installed system)	N/A	YES

Packing list

PN	Description	QTY	Note
93-45103-XXXX	DLAP-211	1	N/A
31-62157-1010-A0	84W, Adapter, 12V/7A, DC Jack Ø2.5	1	Only for Orin NX 16GB
31-62156-1010-A0	60W, Adapter, 12V/5A, DC Jack Ø2.5	1	Only for non-Orin NX 16GB
33-01200-0050	Screw M2.5,P-head,L5	3	N/A
34-34334-0000-A0	VESA bracket	1	N/A
33-04302-0050	Screw M4,I-head,L5.0	4	N/A
33-04603-0080	Screw M4,HW-head,L8.0	4	N/A
47-90004-0010	Technical service card	1	N/A
50-40375-9000	Template A of both CN & TW RoHS Declarat	1	N/A

Optional Accessories

PN	Description	Note
91-49074-000E	Wifi Kit, M2-R8852BE w/ mPCIe converter	Only for Orin series
91-49074-100E	Wifi Kit, M2-AC9260 w/ mPCIe converter	N/A
91-95301-0010	DIN RAIL, DLAP-211 SERIES DIN RAIL set	N/A
91-95277-0010	4G/LET kit, EG25-G 4G/LTE Kit	Only for non-Orin series
95-36400-4E10	M2ASDED4EDE-128GT0-N	NVMe
95-36400-5E10	ASDED4EDE-256GT0-N	NVMe
95-36400-6E10	ASDED4EDE-512GT0-N	NVMe
95-34400-7400	ASDSM4SHE-1TBT0	SATA

Specifications

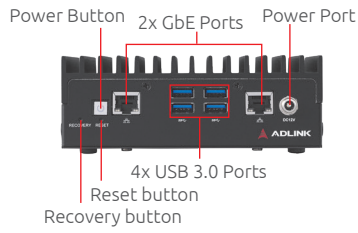
Model	DLAP-211-Orin NX 8GB	DLAP-211-Orin NX 16GB	DLAP-211-Orin Nano 4GB	DLAP-211-Orin Nano 8GB
AI Performance	70 TOPS	100 TOPS	20 TOPS	40 TOPS
System				
GPU	1024-core NVIDIA Ampere GPU with 32 Tensor Cores		512-core NVIDIA Ampere architecture GPU with 16 Tensor Cores	1024-core NVIDIA Ampere architecture GPU with 32 Tensor Cores
CPU	6-core Arm® Cortex®-A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3	8-core Arm® Cortex®-A78AE v8.2 64-bit CPU 2MB L2 + 4MB L3	6-core Arm® Cortex®-A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3	
RAM	8G	16G	4G	8 G
Storage	128GB M.2 2242 PCIe Gen3x4			
OS	Linux® Ubuntu			
Front I/O Interfaces				
Button	1x power, 1x reset, 1x recovery			
HDMI	1x lockable			
USB	4x USB 3.0 Type-A			
Ethernet	2x 10/100/1000Mbps Ethernet			
For S models Only	2x I2-C, 2x SPI, 1x UART, 8x GPIO, 1x Relay through 1x 37pin D sub connector			
Back I/O Interfaces				
USB	1x USB 2.0 OTG			
Serial Port	1x COM RS-232/RS-422/RS-485			
CAN Bus	1x 2.0b			
Extension Slots				
Mini PCIe	1x PCIe mini card slot			
M.2	1x M.2 B key 2242 socket			
Power Supply				
DC Input	12V			
AC Input	60W , OP Temp Max: 45°C	84W ,OP Temp Max: 55°C	60W , OP Temp Max: 45°C	
Mechanical				
Dimensions (W x D x H)	148mm x 120mm x 52mm (DLAP-211-Orin NX/Orin Nano) 148mm x 120mm x 64mm (DLAP-211-Orin NXS/Orin NanoS)			
Weight	Gross 1.7kg/ Net 1.01kg (DLAP-211-Orin NX/Orin Nano) Gross 1.85kg/ Net 1.16kg (DLAP-211-Orin NXS/Orin NanoS)			
Mounting	VESA, DIN rail (optional)			
SMA Antenna Connector	4			
Environmental				
Operating Temperature	-20°C to 70°C with 0.6m/s airflow, at 10W -20°C to 60°C with 0.6m/s airflow, at 15W -20°C to 50°C with 0.6m/s airflow, at 25W -20°C to 40°C with 0.6m/s airflow, at MAXN, Need to use industrial grade parts (which Tamb spec is 85°C) for mPCIe interface parts.			
Operating Humidity	~95% @40°C (non-condensing, optional with fanless solution) without adapter			
Storage Temperature	-40°C to 85°C			
Vibration	Operating 5Grms, 5-500Hz, 3 axes w/M.2 SSD			
Shock	Operating 100G, half sine 11ms duration w/ SD, M.2 SSD			
ESD	Contact ± 4kV, Air ± 8kV			
Regularity	CE & FCC class B, (EN61000-6-4/-6-2), CE-LVD & UL by CB, FCCID			
F/W Support				
WDT	WDT supported			

Specifications

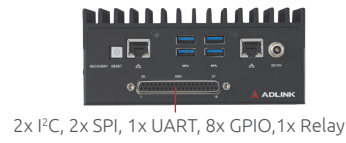
Model	DLAP-211-JNX	DLAP-211-JT2	DLAP-211-Nano
AI Performance	21 TOPS	1.33 TFLOPS	472 GFLOPS
System			
GPU	384-core NVIDIA Volta™ architecture GPU with 48 Tensor Cores	256-core NVIDIA Pascal™ architecture GPU	128-core NVIDIA Maxwell™ architecture GPU
CPU	6-core NVIDIA Carmel ARM® v8.2 64-bit CPU 6MB L2 + 4MB L3	Dual-core NVIDIA Denver™ 2 64-bit CPU and quad-core Arm® Cortex®-A57 MPCore processor	Quad-core ARM® Cortex®-A57 MPCore processo
RAM	8GB/16GB	4GB	
Storage	16 GB eMMC 5.1		
OS	Linux® Ubuntu		
Front I/O Interfaces			
Button	1x power, 1x reset, 1x recovery		
HDMI	1x lockable		
USB	4x USB 3.0 Type-A		
Ethernet	2x 10/100/1000Mbps Ethernet		
For S models Only	2x I2-C, 2x SPI, 1x UART, 8x GPIO, 1x Relay through 1x 37pin D sub connector		
Back Panel I/O Ports			
USB	1x USB 2.0 OTG		
Serial Port	1x COM RS-232/RS-422/RS-485		
CAN Bus	1x 2.0b	N/A	
Extension Slots			
Mini PCIe	1x PCIe mini card slot		
M.2	1x M.2 B key 2242 socket		
SD Card Slot	1x SD card slot		
Power Supply			
DC Input	12V		
AC Input	60W, OP Temp Max: 55°C		
Mechanical			
Dimensions (W x D x H)	148mm x 120mm x 52mm 148mm x 120mm x 64mm (S models)		
Weight	Gross 1.7kg/ Net 1.01kg Gross 1.85kg/ Net 1.16kg (S models)		
Mounting	VESA, DIN rail (optional)		
SMA Antenna Connector	4		
Environmental			
Operating Temperature	-20°C to 70C with 0.6m/s airflow, at 10W -20°C to 60°C with 0.6m/s airflow, at 15W Need to use industrial grade parts (which Tamb spec is 85°C) for mPCIe interface parts.		
Operating Humidity	~95% @40°C (non-condensing, optional with fanless solution) without adapter		
Storage Temperature	-40°C to 85°C		
Vibration	Operating 5Grms, 5-500Hz, 3 axes w/M.2 SSD		
Shock	Operating 100G, half sine 11ms duration w/ SD, M.2 SSD		
ESD	Contact ± 4kV, Air ± 8kV		
Regularity	CE & FCC class B, (EN61000-6-4/-6-2), CE-LVD & UL by CB, FCCID		
F/W Support			
WDT	WDT supported		

I/O View

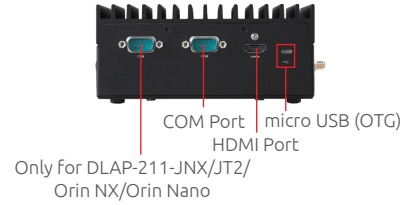
DLAP-211-JNX/JT2/Nano/Orin NX/Orin Nano



DLAP-211-JNXS/JT2S/NanoS
Orin NXS/Orin NanoS

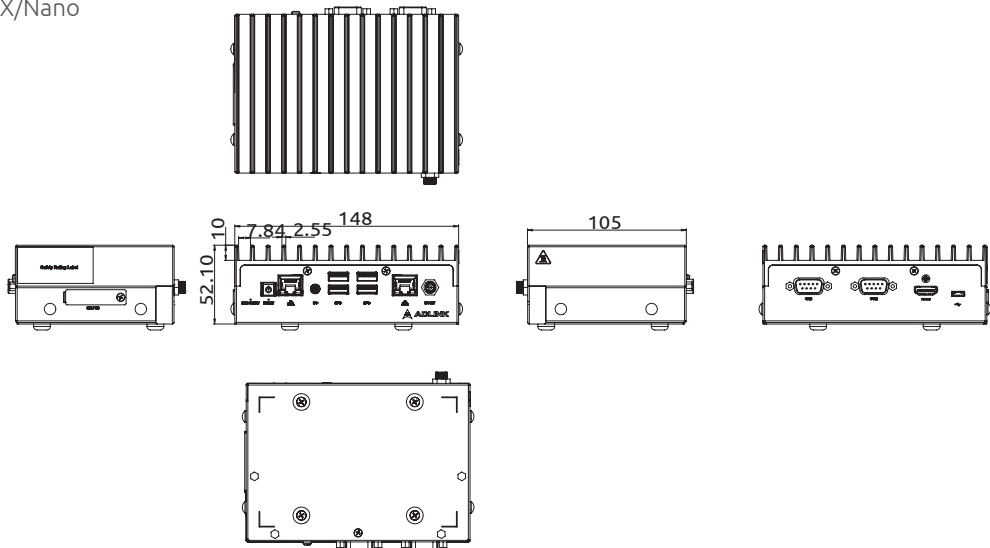


DLAP-211 Series (backside)



Product Dimensions and Illustration

DLAP-211-JNX/JT2/Nano
DLAP-211-Orin NX/Nano



DLAP-211-JNXS/JT2S/NanoS
DLAP-211-Orin NXS/NanoS

